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U.S. DEPARTMENT OF COMMERCE PATENT & TRADEMARK OFFICE									Atty. Docket No.	Serial No. 0	Serial No. 08/909,489		
INFORMATION DISCLOSURE									Applicant: Charles I. Peddle				
STATEMENT BY APPLICANT								Γ	Filing date: 12 August 1997		Group: 2786		
U.S. PATENT DOCUMENTS													
Examiner Initials	Document Number Date								Name	Class	Sub-Class	Filing Date if approp	
Qs.	5	4	4	4	3	6	6	12/22/95	Chiu	324	1046	IPE	
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APPLICANT'S ANALYSIS

This Information Disclosure Statement covers four U.S. patents cited in the published copy of PCT application PCT/US97/14204. Published December 9, 1997. The attached International Search Report classifies the cited patent as as being in category "A", i.e., "documents defining the general state of the art which are not considered to be of particular relevance."

The four cited patents have been carefully studied and it is believed that they are not relevant to any claim now in this application.

Specifically, <u>Chiu</u> relates to testing and burn in-of devices on a wafer, removal of defective devices, and replacement with good devices.

<u>Usami</u>, replaces defective macro cells before integration into larger collections of components. Usami replaces in total, as opposed to substitution of defective lines in one unit with operational lines from an independent unit.

Friedman studies the patterns of occurrence of defects in wafers to find possible correlation between defect mapping in a wafer and the process steps in forming the structures on the wafer.

Logue constructs "A" and "B" wafers which are mirror images. Defective circuits on "A" wafers are physically replaced with operational circuits removed from a "B" wafer.